

CIRCUIT BOARD PLANE INTERLEAVE APPARATUS AND METHOD

Abstract of the Disclosure

A circuit board is provided. The circuit board includes two conductive layers, either horizontally-opposed, or vertically-overlapping, formed around a dielectric layer. Mutually-engaging interstices or tongues and grooves are formed in each conductive layer, with the dielectric disposed between them. The interstices (or tongues and grooves) are typically formed in a complementary shape, but this is not necessary. Any number of interstices and/or tongues and grooves may be formed into the conductive layers. The amount of engagement between the interstices, or the amount each conductive layer overlaps the other along its width, may be selected to provide a predetermined amount of capacitance between the conductive layers. The dielectric layer dielectric constant may also be selected in order to adjust the capacitance formed between the conductive layers. Other embodiments of the invention include electronic circuits and methods for constructing the disclosed circuit boards and related electronic circuits.

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